**FIFO PRODUCTS**

**Ordering Information**

**Package Description Table**

<table>
<thead>
<tr>
<th>IDT ID</th>
<th>Abbr</th>
<th>Description</th>
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<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>D</td>
<td>CERDIP</td>
<td>Ceramic Dual In-Line Package</td>
<td>T</td>
<td>PDIP</td>
<td>Plastic Dual In-Line Package</td>
</tr>
<tr>
<td>TD</td>
<td>CERDIP</td>
<td>Ceramic Dual In-Line Package</td>
<td>J</td>
<td>PLCC</td>
<td>Plastic Leaded Chip Carrier</td>
</tr>
<tr>
<td>BC</td>
<td>CABGA</td>
<td>Chip Array Ball Grid Array</td>
<td>PQF</td>
<td>PQFP</td>
<td>Plastic Quad Flat Package</td>
</tr>
<tr>
<td>L</td>
<td>LCC</td>
<td>Leadless Chip Carrier (Ceramic) - ml only</td>
<td>SO</td>
<td>SOIC</td>
<td>Small Outline Integrated Circuit (Plastic)</td>
</tr>
<tr>
<td>BB</td>
<td>PBGA</td>
<td>Plastic Ball Grid Array</td>
<td>PF</td>
<td>TQFP</td>
<td>Thin Quad Flat Package (Plastic)</td>
</tr>
<tr>
<td>BG</td>
<td>PBGA</td>
<td>Plastic Ball Grid Array</td>
<td>TF</td>
<td>TQFP</td>
<td>Thin Quad Flat Package (Plastic)</td>
</tr>
<tr>
<td>P</td>
<td>PDIP</td>
<td>Plastic Dual In-line Package</td>
<td>PA</td>
<td>TSSOP</td>
<td>Thin Shrink (Plastic) Small Outline Package</td>
</tr>
</tbody>
</table>

**FIFO PRODUCTS**

**Part Number Description**

- **A** = Alpha character
- **N** = Numeric character

**Tape & Reel:** Optional 8 suffix at end of part number indicates Tape & Reel packaging.
- **B** = tape & reel
- **Blank** = tube or trays

**Temperature**

- **None** = Commercial (0° C - 70° C)
- **I** = Industrial (-40° C - 85° C)
- **B** = Military: To MIL-STD-883, method 5004, class B

**Green**

- **None** = Standard Packaging
- **G** = Green packaging

**Package**

See package description above

**Speed**

Guaranteed minimum performance measured in nanoseconds or MHz

**Device Type**

- 0 - 4, 7: Single FIFOs
- 8: Dual FIFOs
- 5: Quad FIFOs

**Voltage**

- **None:** 5.0 V
- V: 3.3V
- **T:** 2.5V

**Product Family**

72: FIFO (example 72V36110L6BB)